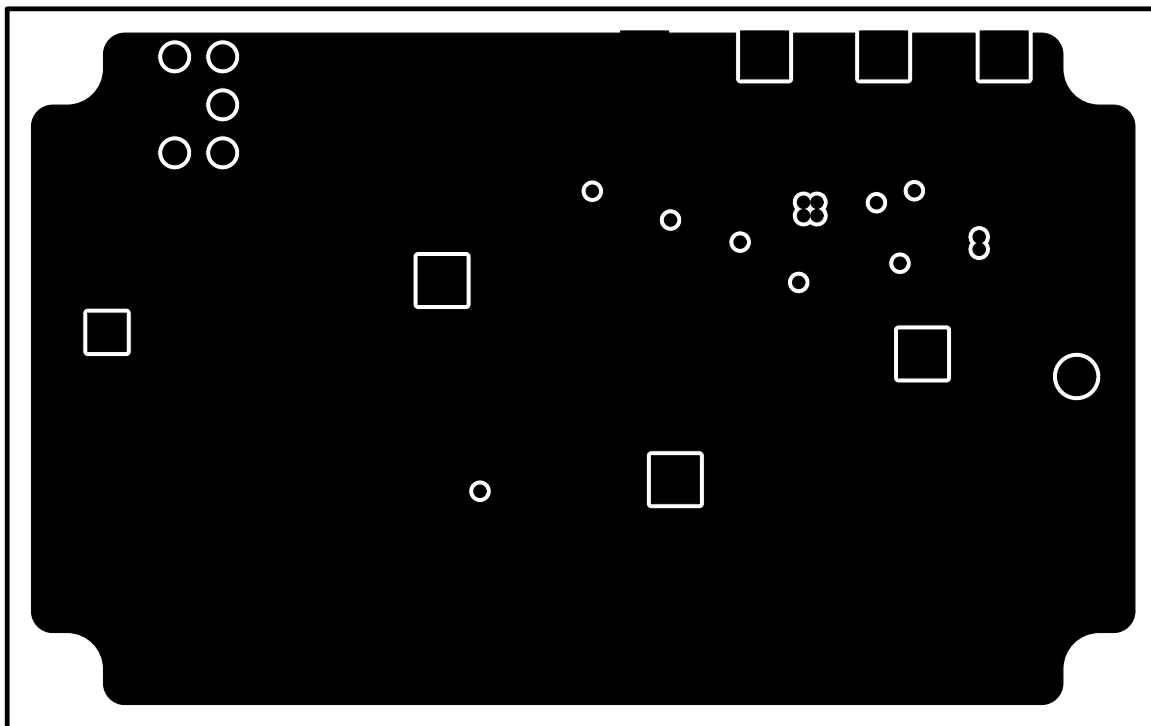
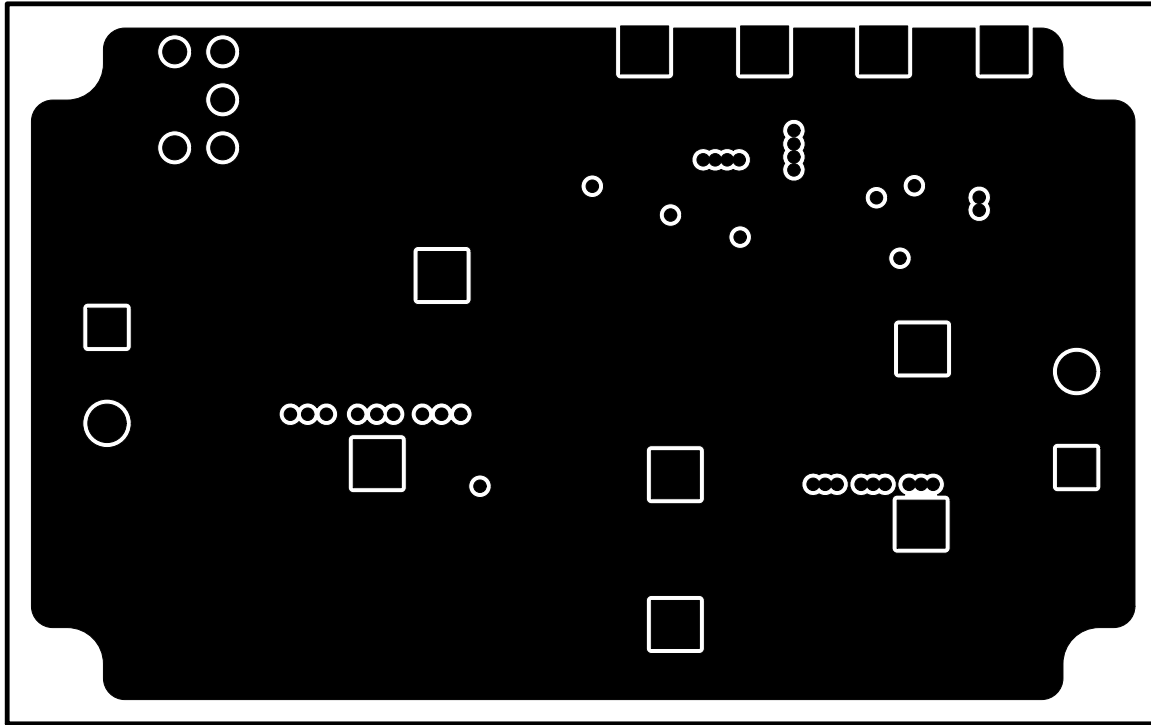


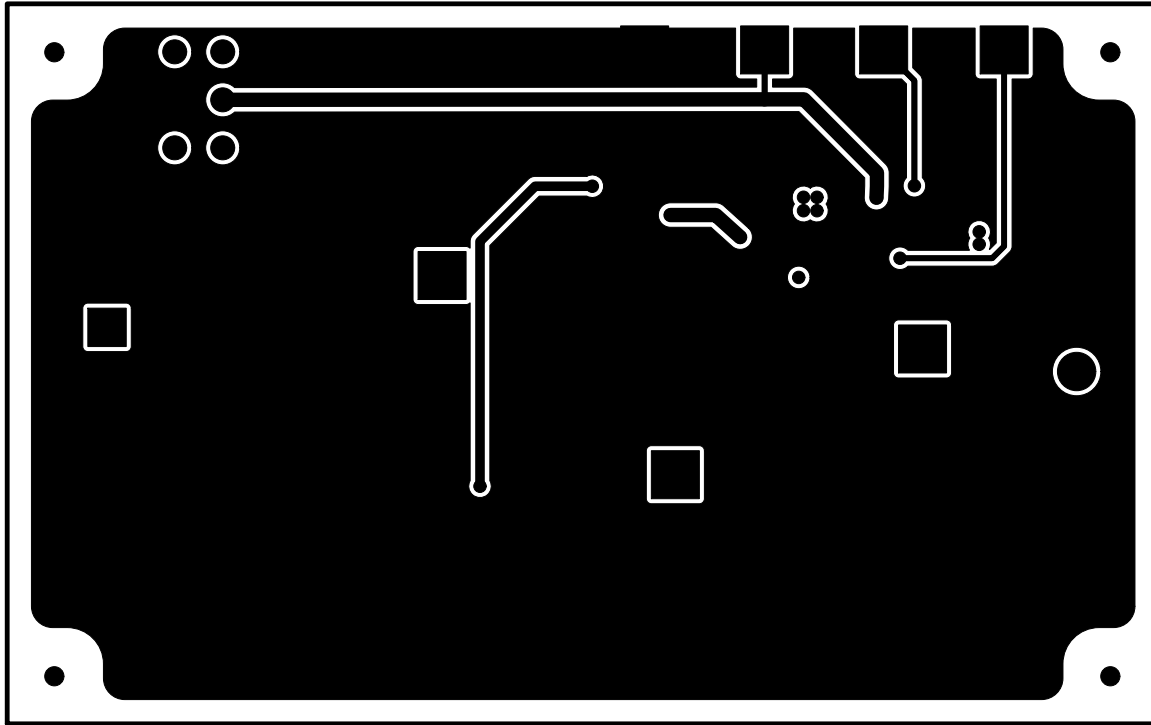
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P M					
		Top	Internal	Bot	Top	Bot	Top	Bot	Top					
Board No.	PWR126	Rev.	A	L1										
Date:	2/10/2012	Filename:	PWR126A.pcb	Engineer:	Na Kong	PCB Dsgnr:	E Archambault	Modified Date:	02/22/2012					



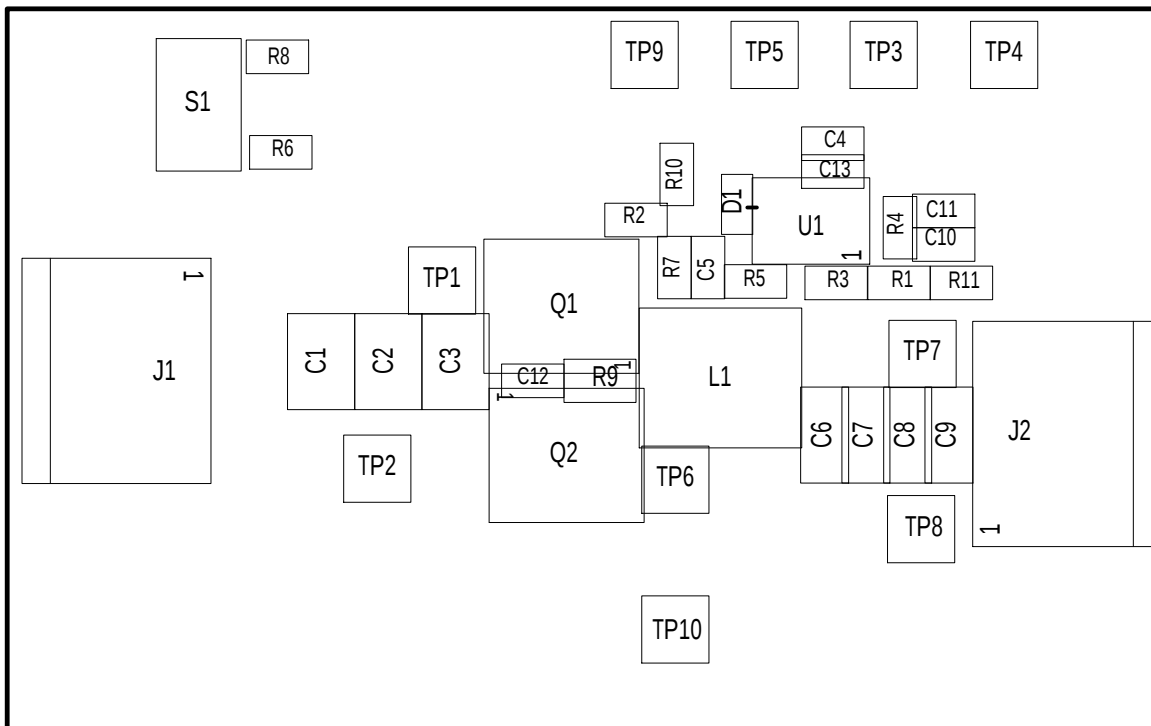
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P M		
		Top	Internal	Bot	Top	Bot	Top	Bot	Top		
Board No.	PWR126	Rev.	A		L2						
Date:	2/10/2012	Filename:	PWR126A.pcb	Engineer:	Na Kong	PCB Dsgnr:	E Archambault	Modified Date:	02/22/2012		



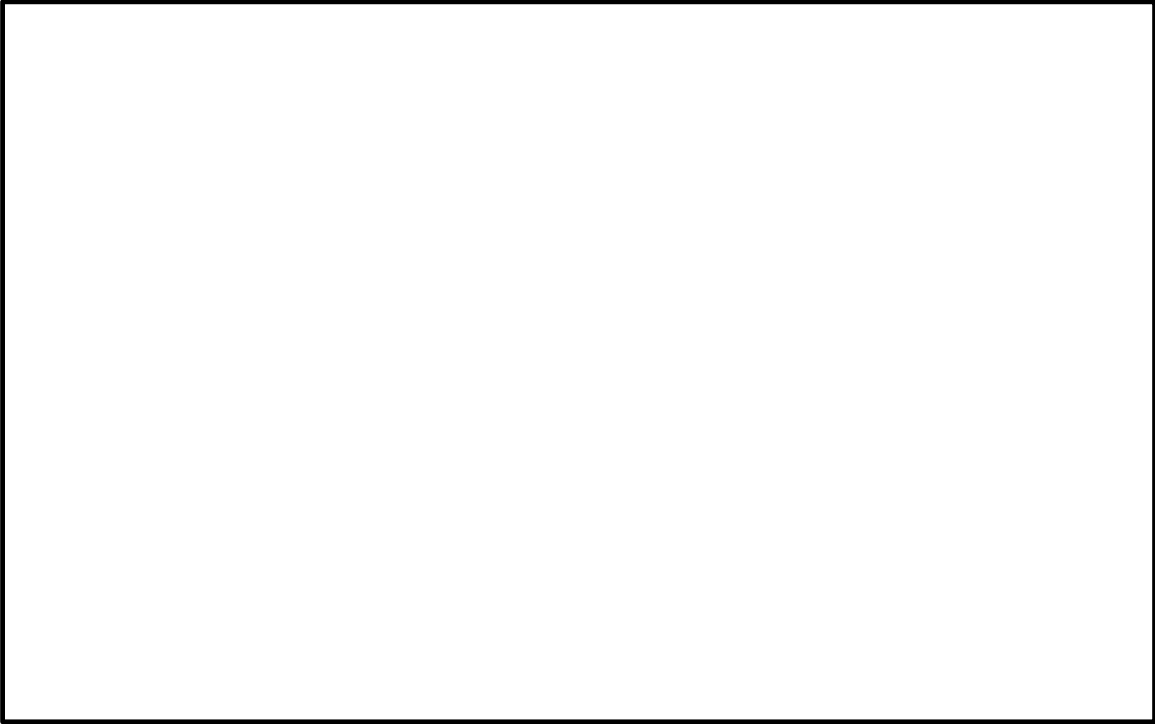
TEXAS INSTRUMENTS				Copper Layer Name			Silkscreen		S Mask		P M
				Top	Internal	Bot	Top	Bot	Top	Bot	Top
Board No.	PWR126	Rev.	A			L3					
Date:	2/10/2012	Filename:	PWR126A.pcb	Engineer:	Na Kong	PCB Dsgnr:	E Archambault	Modified Date:	02/22/2012		



TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P M	
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	
Board No.	PWR126	Rev.	A				L4				
Date:	2/10/2012	Filename:	PWR126A.pcb	Engineer:	Na Kong	PCB Dsgnr:	E Archambault	Modified Date:	02/22/2012		



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P M	
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	
Board No.	PWR126	Rev.	A	L1						
Date:	2/10/2012	Filename:	PWR126A.pcb	Engineer:	Na Kong	PCB Dsgnr:	E Archambault	Modified Date:	02/22/2012	



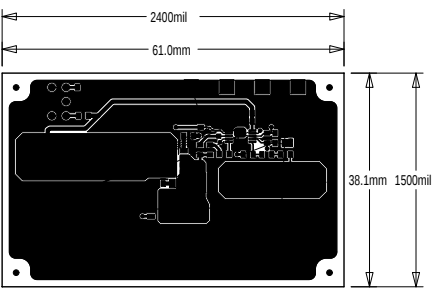
Date:		2/10/2015	Filename:	PWR126A.pcb	Engineer:	Ng Kong	PCB Design:	E Archambault	Modified Date:	02/22/2015		
Board No.		PWR126	Rev.	A	Top	Internal	Bot	Top	Bot	Top	Bot	2 Mask
TEXAS INSTRUMENTS												
Copper Layer Name: 2 Mask												

FABRICATION CHART

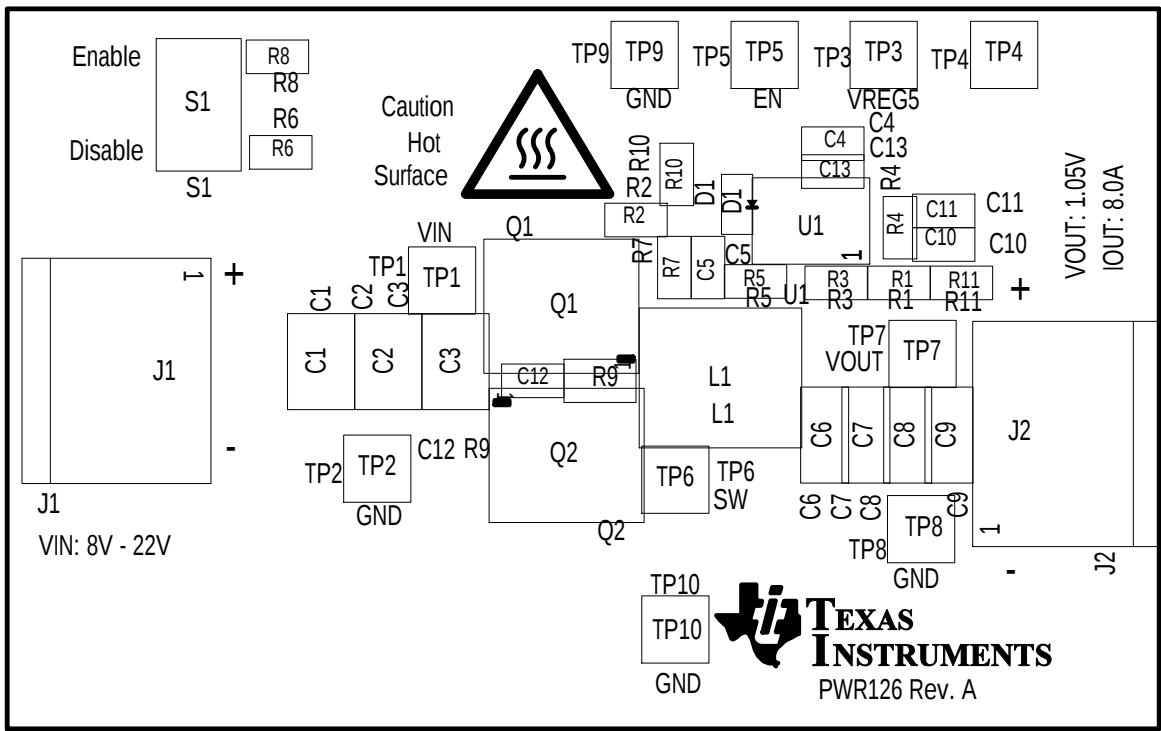
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
<input type="checkbox"/> 0.031 <input checked="" type="checkbox"/> 0.062 <input type="checkbox"/> 0.093 <input type="checkbox"/> 0.125	<input checked="" type="checkbox"/> LAYER 1 <input type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input checked="" type="checkbox"/> LAYER 1 <input type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____	<input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____
DESIGN	TRACE/GAP SPACING		LAYER COUNT	
<input type="checkbox"/> SMD <input type="checkbox"/> THRU-HOLE <input checked="" type="checkbox"/> MIX	<input type="checkbox"/> 0.010/0.010 <input checked="" type="checkbox"/> 0.008/0.008 <input type="checkbox"/> 0.006/0.006		<input type="checkbox"/> SINGLE SIDED <input checked="" type="checkbox"/> 4 LAYER <input type="checkbox"/> 8 LAYER <input type="checkbox"/> OTHER _____	<input type="checkbox"/> 2 LAYER <input type="checkbox"/> 6 LAYER <input type="checkbox"/> 10 LAYER

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:** ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
- BASE LAMINATE:** PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 4 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
- SOLDERMASK:** SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
- TOLERANCES:** UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
- PLATING:** HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
- FINISH:** PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
- LEGEND:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
- MARKINGS:** BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
- WORKMANSHIP:** BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
- DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
- PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
- PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
Board No.	Rev.	Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
PWR126	A	L1											FB
Date: 2/10/2012	Filename: PWR126A.pcb	Engineer: Na Kong	PCB Designer: E. Richambault	Modified Date: 02/22/2012	Time Stamp: 09:04:55								



<h1 style="text-align: center;">TEXAS INSTRUMENTS</h1>				Copper Layer Name			Silkscreen		S Mask		P M
				Top	Internal	Bot	Top	Bot	Top	Bot	Top
Board No. PWR126				Rev. A			L1		S1		
Date: 2/10/2012		Filename: PWR126A.pcb		Engineer: Na Kong		PCB Dsgnr: E Archambault		Modified Date: 02/22/2012			

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